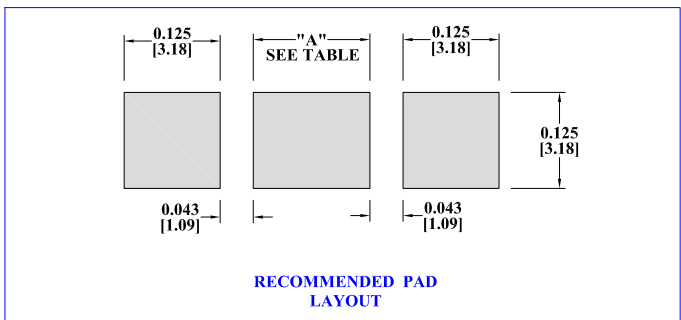


NOTES:

- 1) Dielectric Withstanding Voltage: 300 VDC.
- 2) Insulation Resistance: 10 G Ohms Minimum.
- 3) Inductance in Pi Circuits is typically 0.1 μH minimum.
- 4) Electrode terminations are post assembly solder dipped (Alloy - SAC305).
- 5) Each filter is constructed with High Melting Point solder alloy (SN10/PB88/AG2). Filters are RoHS Compliant.
- 6) Insertion Loss values are typical, and are for shielded applications. Open PCB applications may vary.
- 7) Custom capacitance values and tolerances are available.
- 8) Standard packaging is Tape and Reel. Quantities up to 1000 pieces are supplied on a 7" reel. Larger quantities are supplied on a 13" reel with up to 7000 pieces per reel. Bulk packaging is optional.
- 9) The center (Ground) pad is different for SMP1/SMC1 versus SMP2/SMC2 filters. See the Pad Layout drawing and the table below for details.



PART NUMBER	WVDC (125°C)	CAP. (pF)	TOL.	CURRENT (A)	PAD LAYOUT "A"	TYPICAL INSERTION LOSS (dB) PER MIL-STD-220 @ 25°C		
						10 MHz	100 MHz	1 GHz
SMP SERIES - PI CIRCUITS								
SMP1-01-101Z	100	100	+80/-20%	10	.102	-	3	16
SMP1-01-471Z	100	470	+80/-20%	10	.102	1	16	40
SMP1-01-102P	100	1000	+100/-0%	10	.102	7	40	65
SMP1-01-202P	100	2000	+100/-0%	10	.102	10	45	70
SMP1-01-402Z	100	4000	+80/-20%	10	.102	13	52	70
SMP2-01-682Z	100	6800	+80/-20%	10	.202	16	60	70
SMP2-01-822Z	100 (85°C)	8200	+80/-20%	10	.202	20	65	70
SMC SERIES - C CIRCUITS								
SMC1-01-101Z	100	100	+80/-20%	20	.102	-	1	16
SMC1-01-471Z	100	470	+80/-20%	20	.102	-	12	27
SMC1-01-102Z	100	1000	+80/-20%	20	.102	3	20	35
SMC1-01-152Z	100	1500	+80/-20%	20	.102	5	22	37
SMC1-01-252Z	100	2500	+80/-20%	20	.102	10	25	40
SMC1-01-402Z	100	4000	+80/-20%	20	.102	13	30	45
SMC2-01-682Z	100	6800	+80/-20%	20	.202	16	35	50
SMC2-01-822Z	100 (85°C)	8200	+80/-20%	20	.202	20	40	55

PRODUCT INSTALLATION RECOMMENDATIONS

SOLDERING

Corry Micronics SMP and SMC Surface Mount Filters can be assembled onto printed circuit boards using all industry standard soldering methods including vapor phase reflow, wave solder, infrared reflow, convection reflow (hot air), and hand soldering (soldering iron). All electrode terminations include a Nickel barrier layer and Tin overplating that provides excellent solderability.

SMP and SMC Surface Mount Filters are compatible with standard RoHS assembly methods. SAC305 (96.5% Sn/3% Ag/0.5%Cu) or SAC387 (95.5% Sn/3.8% Ag/0.7% Cu) solder paste with RMA flux systems are recommended. For non-RoHS applications, SN60, SN62, or SN63 solder pastes can be used.

Care should be taken to properly adjust the reflow profile to avoid undue thermal shock to the ceramic dielectric used in these components. Standard reflow profiles that do not exceed a temperature rate of change greater than 5°F (2.7°C)/Second should be used. Dwell time above the reflow temperature of the solder paste being used should be kept to a minimum.

In cases where hand soldering is used, it is recommended that the tip of the soldering iron should not be allowed to touch the body of the filter, but rather should only come in contact with the solder fillet area of the joint being reflowed. Soldering iron tips should also be controlled to a temperature of 500°F (260°C) Max.

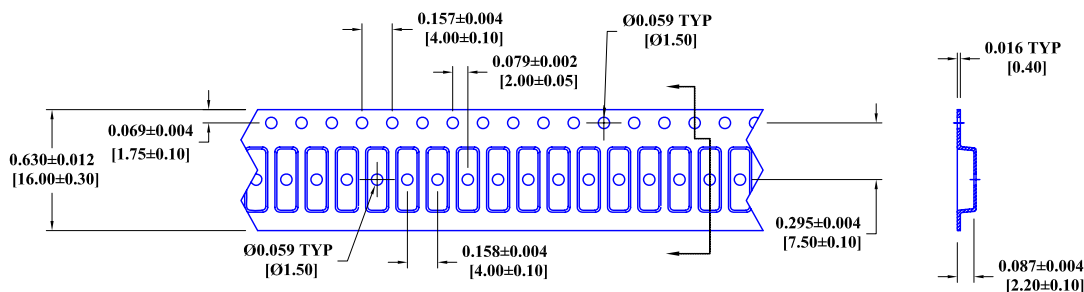
CLEANING

SMP and SMC Surface Mount Filters can be cleaned in most industry standard, water-based and solvent-based cleaning systems.

PACKAGING

Standard delivery of SMP and SMC Surface Mount Filters are on Tape and Reel. Packaging used is in accordance with industry standards for taping of surface mount components for automatic placement. Reference IEC-286-3, Type II and EIA-481-A

16 mm embossed carrier tape is used for these components. See the drawing below for component pitch and indexing information.



COMPANY INFORMATION

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